



Welcome to [E-XFL.COM](https://www.e-xfl.com)

What is "[Embedded - Microcontrollers](#)"?

"[Embedded - Microcontrollers](#)" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "[Embedded - Microcontrollers](#)"

Details

Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	4MHz
Connectivity	-
Peripherals	Brown-out Detect/Reset, POR, WDT
Number of I/O	13
Program Memory Size	3.5KB (2K x 14)
Program Memory Type	OTP
EEPROM Size	-
RAM Size	128 x 8
Voltage - Supply (Vcc/Vdd)	2.5V ~ 5.5V
Data Converters	-
Oscillator Type	External
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Surface Mount
Package / Case	18-SOIC (0.295", 7.50mm Width)
Supplier Device Package	18-SOIC
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16lc622a-04e-so

PIC16C62X

NOTES:

PIC16C62X

FIGURE 4-6: DATA MEMORY MAP FOR THE PIC16C620A/CR620A/621A

File Address			File Address
00h	INDF ⁽¹⁾	INDF ⁽¹⁾	80h
01h	TMR0	OPTION	81h
02h	PCL	PCL	82h
03h	STATUS	STATUS	83h
04h	FSR	FSR	84h
05h	PORTA	TRISA	85h
06h	PORTB	TRISB	86h
07h			87h
08h			88h
09h			89h
0Ah	PCLATH	PCLATH	8Ah
0Bh	INTCON	INTCON	8Bh
0Ch	PIR1	PIE1	8Ch
0Dh			8Dh
0Eh		PCON	8Eh
0Fh			8Fh
10h			90h
11h			91h
12h			92h
13h			93h
14h			94h
15h			95h
16h			96h
17h			97h
18h			98h
19h			99h
1Ah			9Ah
1Bh			9Bh
1Ch			9Ch
1Dh			9Dh
1Eh			9Eh
1Fh	CMCON	VRCON	9Fh
20h	General Purpose Register		A0h
6Fh	General Purpose Register	Accesses 70h-7Fh	F0h
70h			
7Fh			FFh
	Bank 0	Bank 1	

☐ Unimplemented data memory locations, read as '0'.
Note 1: Not a physical register.

FIGURE 4-7: DATA MEMORY MAP FOR THE PIC16C622A

File Address			File Address
00h	INDF ⁽¹⁾	INDF ⁽¹⁾	80h
01h	TMR0	OPTION	81h
02h	PCL	PCL	82h
03h	STATUS	STATUS	83h
04h	FSR	FSR	84h
05h	PORTA	TRISA	85h
06h	PORTB	TRISB	86h
07h			87h
08h			88h
09h			89h
0Ah	PCLATH	PCLATH	8Ah
0Bh	INTCON	INTCON	8Bh
0Ch	PIR1	PIE1	8Ch
0Dh			8Dh
0Eh		PCON	8Eh
0Fh			8Fh
10h			90h
11h			91h
12h			92h
13h			93h
14h			94h
15h			95h
16h			96h
17h			97h
18h			98h
19h			99h
1Ah			9Ah
1Bh			9Bh
1Ch			9Ch
1Dh			9Dh
1Eh			9Eh
1Fh	CMCON	VRCON	9Fh
20h	General Purpose Register	General Purpose Register	A0h
			BFh
			C0h
6Fh	General Purpose Register	Accesses 70h-7Fh	F0h
70h			
7Fh			FFh
	Bank 0	Bank 1	

☐ Unimplemented data memory locations, read as '0'.
Note 1: Not a physical register.

4.2.2.2 OPTION Register

The OPTION register is a readable and writable register, which contains various control bits to configure the TMR0/WDT prescaler, the external RB0/INT interrupt, TMR0 and the weak pull-ups on PORTB.

Note: To achieve a 1:1 prescaler assignment for TMR0, assign the prescaler to the WDT (PSA = 1).

REGISTER 4-2: OPTION REGISTER (ADDRESS 81H)

R/W-1	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1
RBPU	INTEDG	T0CS	T0SE	PSA	PS2	PS1	PS0
bit 7							bit 0

- bit 7 **RBPU: PORTB Pull-up Enable bit**
 1 = PORTB pull-ups are disabled
 0 = PORTB pull-ups are enabled by individual port latch values
- bit 6 **INTEDG: Interrupt Edge Select bit**
 1 = Interrupt on rising edge of RB0/INT pin
 0 = Interrupt on falling edge of RB0/INT pin
- bit 5 **T0CS: TMR0 Clock Source Select bit**
 1 = Transition on RA4/T0CKI pin
 0 = Internal instruction cycle clock (CLKOUT)
- bit 4 **T0SE: TMR0 Source Edge Select bit**
 1 = Increment on high-to-low transition on RA4/T0CKI pin
 0 = Increment on low-to-high transition on RA4/T0CKI pin
- bit 3 **PSA: Prescaler Assignment bit**
 1 = Prescaler is assigned to the WDT
 0 = Prescaler is assigned to the Timer0 module
- bit 2-0 **PS<2:0>: Prescaler Rate Select bits**

Bit Value	TMR0 Rate	WDT Rate
000	1 : 2	1 : 1
001	1 : 4	1 : 2
010	1 : 8	1 : 4
011	1 : 16	1 : 8
100	1 : 32	1 : 16
101	1 : 64	1 : 32
110	1 : 128	1 : 64
111	1 : 256	1 : 128

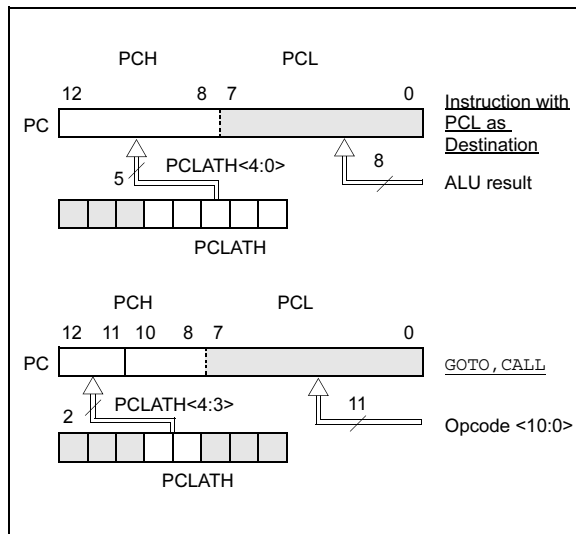
Legend:

R = Readable bit W = Writable bit U = Unimplemented bit, read as '0'
 - n = Value at POR '1' = Bit is set '0' = Bit is cleared x = Bit is unknown

4.3 PCL and PCLATH

The program counter (PC) is 13-bits wide. The low byte comes from the PCL register, which is a readable and writable register. The high byte (PC<12:8>) is not directly readable or writable and comes from PCLATH. On any RESET, the PC is cleared. Figure 4-8 shows the two situations for the loading of the PC. The upper example in the figure shows how the PC is loaded on a write to PCL (PCLATH<4:0> → PCH). The lower example in the figure shows how the PC is loaded during a CALL or GOTO instruction (PCLATH<4:3> → PCH).

FIGURE 4-8: LOADING OF PC IN DIFFERENT SITUATIONS



4.3.1 COMPUTED GOTO

A computed GOTO is accomplished by adding an offset to the program counter (ADDWF PCL). When doing a table read using a computed GOTO method, care should be exercised if the table location crosses a PCL memory boundary (each 256 byte block). Refer to the application note, "Implementing a Table Read" (AN556).

4.3.2 STACK

The PIC16C62X family has an 8-level deep x 13-bit wide hardware stack (Figure 4-2 and Figure 4-3). The stack space is not part of either program or data space and the stack pointer is not readable or writable. The PC is PUSHed onto the stack when a CALL instruction is executed or an interrupt causes a branch. The stack is POPed in the event of a RETURN, RETLW or a RETFIE instruction execution. PCLATH is not affected by a PUSH or POP operation.

The stack operates as a circular buffer. This means that after the stack has been PUSHed eight times, the ninth push overwrites the value that was stored from the first push. The tenth push overwrites the second push (and so on).

Note 1: There are no STATUS bits to indicate stack overflow or stack underflow conditions.

2: There are no instructions/mnemonics called PUSH or POP. These are actions that occur from the execution of the CALL, RETURN, RETLW and RETFIE instructions, or the vectoring to an interrupt address.

PIC16C62X

5.2 PORTB and TRISB Registers

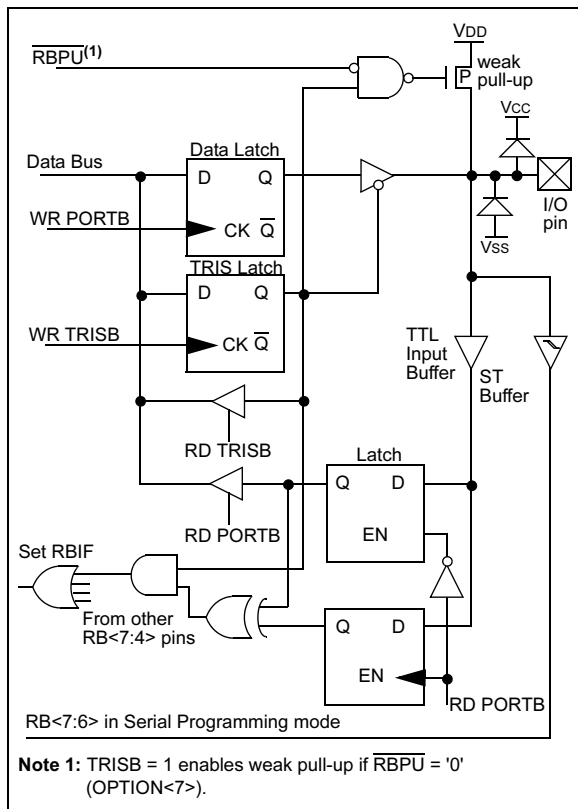
PORTB is an 8-bit wide, bi-directional port. The corresponding data direction register is TRISB. A '1' in the TRISB register puts the corresponding output driver in a High Impedance mode. A '0' in the TRISB register puts the contents of the output latch on the selected pin(s).

Reading PORTB register reads the status of the pins, whereas writing to it will write to the port latch. All write operations are read-modify-write operations. So a write to a port implies that the port pins are first read, then this value is modified and written to the port data latch.

Each of the PORTB pins has a weak internal pull-up ($\approx 200 \mu\text{A}$ typical). A single control bit can turn on all the pull-ups. This is done by clearing the RBPV (OPTION<7>) bit. The weak pull-up is automatically turned off when the port pin is configured as an output. The pull-ups are disabled on Power-on Reset.

Four of PORTB's pins, RB<7:4>, have an interrupt on change feature. Only pins configured as inputs can cause this interrupt to occur (e.g., any RB<7:4> pin configured as an output is excluded from the interrupt on change comparison). The input pins (of RB<7:4>) are compared with the old value latched on the last read of PORTB. The "mismatch" outputs of RB<7:4> are OR'ed together to generate the RBIF interrupt (flag latched in INTCON<0>).

FIGURE 5-5: BLOCK DIAGRAM OF RB<7:4> PINS



This interrupt can wake the device from SLEEP. The user, in the interrupt service routine, can clear the interrupt in the following manner:

- Any read or write of PORTB. This will end the mismatch condition.
- Clear flag bit RBIF.

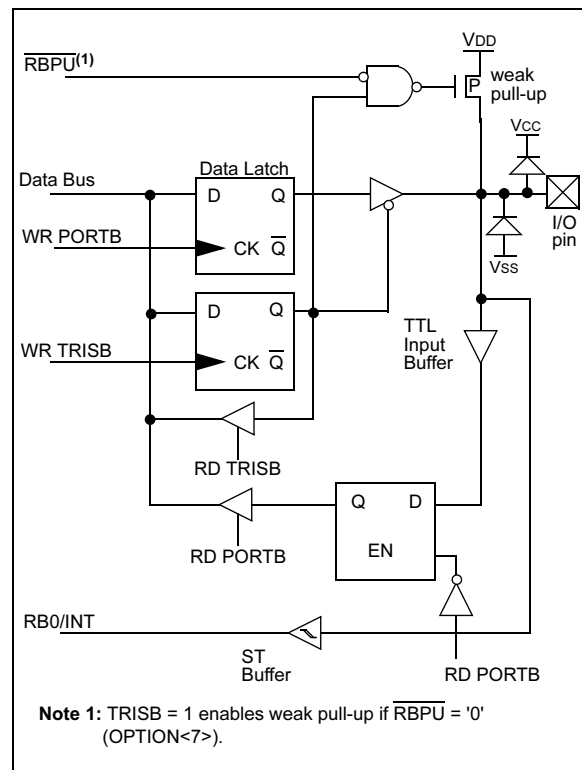
A mismatch condition will continue to set flag bit RBIF. Reading PORTB will end the mismatch condition and allow flag bit RBIF to be cleared.

This interrupt on mismatch feature, together with software configurable pull-ups on these four pins allow easy interface to a key pad and make it possible for wake-up on key-depression. (See AN552, "Implementing Wake-Up on Key Strokes.")

Note: If a change on the I/O pin should occur when the read operation is being executed (start of the Q2 cycle), then the RBIF interrupt flag may not get set.

The interrupt-on-change feature is recommended for wake-up on key depression operation and operations where PORTB is only used for the interrupt on change feature. Polling of PORTB is not recommended while using the interrupt-on-change feature.

FIGURE 5-6: BLOCK DIAGRAM OF RB<3:0> PINS



6.0 TIMER0 MODULE

The Timer0 module timer/counter has the following features:

- 8-bit timer/counter
- Readable and writable
- 8-bit software programmable prescaler
- Internal or external clock select
- Interrupt on overflow from FFh to 00h
- Edge select for external clock

Figure 6-1 is a simplified block diagram of the Timer0 module.

Timer mode is selected by clearing the T0CS bit (OPTION<5>). In Timer mode, the TMR0 will increment every instruction cycle (without prescaler). If Timer0 is written, the increment is inhibited for the following two cycles (Figure 6-2 and Figure 6-3). The user can work around this by writing an adjusted value to TMR0.

Counter mode is selected by setting the T0CS bit. In this mode, Timer0 will increment either on every rising or falling edge of pin RA4/T0CKI. The incrementing edge is determined by the source edge (T0SE) control bit (OPTION<4>). Clearing the T0SE bit selects the rising edge. Restrictions on the external clock input are discussed in detail in Section 6.2.

The prescaler is shared between the Timer0 module and the Watchdog Timer. The prescaler assignment is controlled in software by the control bit PSA (OPTION<3>). Clearing the PSA bit will assign the prescaler to Timer0. The prescaler is not readable or writable. When the prescaler is assigned to the Timer0 module, prescale value of 1:2, 1:4, ..., 1:256 are selectable. Section 6.3 details the operation of the prescaler.

6.1 TIMER0 Interrupt

Timer0 interrupt is generated when the TMR0 register timer/counter overflows from FFh to 00h. This overflow sets the T0IF bit. The interrupt can be masked by clearing the T0IE bit (INTCON<5>). The T0IF bit (INTCON<2>) must be cleared in software by the Timer0 module interrupt service routine before re-enabling this interrupt. The Timer0 interrupt cannot wake the processor from SLEEP, since the timer is shut off during SLEEP. See Figure 6-4 for Timer0 interrupt timing.

FIGURE 6-1: TIMER0 BLOCK DIAGRAM

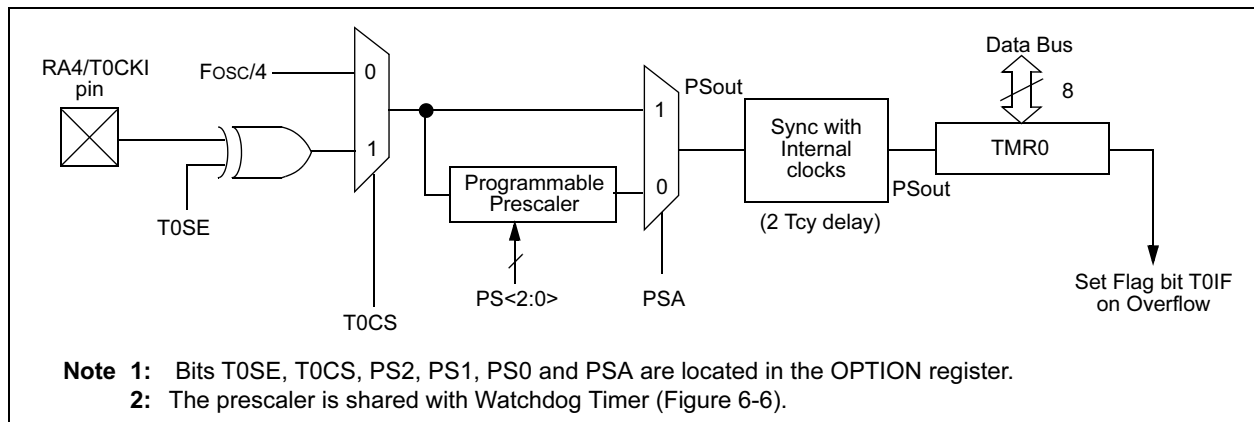
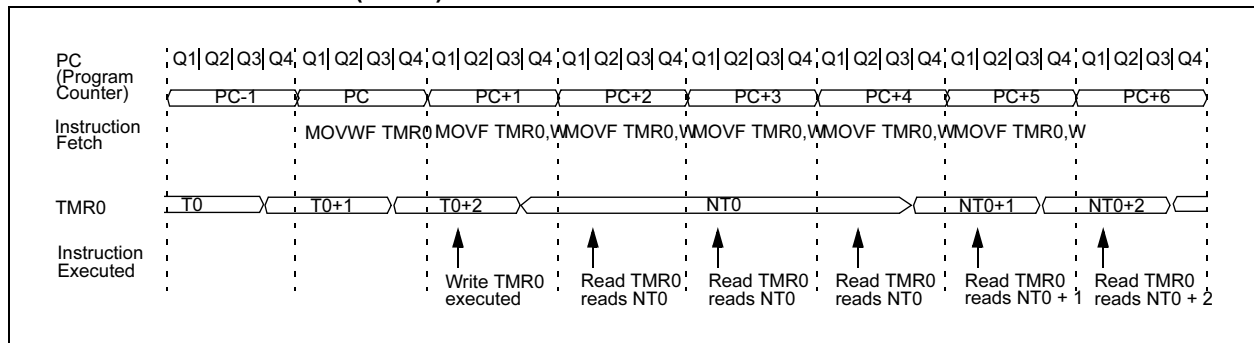


FIGURE 6-2: TIMER0 (TMR0) TIMING: INTERNAL CLOCK/NO PRESCALER



6.3.1 SWITCHING PRESCALER ASSIGNMENT

The prescaler assignment is fully under software control (i.e., it can be changed “on-the-fly” during program execution). To avoid an unintended device RESET, the following instruction sequence (Example 6-1) must be executed when changing the prescaler assignment from Timer0 to WDT.)

EXAMPLE 6-1: CHANGING PRESCALER (TIMER0→WDT)

```

1.BCF      STATUS, RP0    ;Skip if already in
                           ;Bank 0
2.CLRWDT                      ;Clear WDT
3.CLRF      TMR0          ;Clear TMR0 & Prescaler
4.BSF      STATUS, RP0    ;Bank 1
5.MOVLW     '00101111'b;  ;These 3 lines (5, 6, 7)
6.MOVWF     OPTION        ;are required only if
                           ;desired PS<2:0> are
7.CLRWDT                      ;000 or 001
8.MOVLW     '00101xxx'b   ;Set Postscaler to
9.MOVWF     OPTION        ;desired WDT rate
10.BCF      STATUS, RP0    ;Return to Bank 0
    
```

To change prescaler from the WDT to the TMR0 module, use the sequence shown in Example 6-2. This precaution must be taken even if the WDT is disabled.

EXAMPLE 6-2: CHANGING PRESCALER (WDT→TIMER0)

```

CLRWDT                      ;Clear WDT and
                           ;prescaler
BSF      STATUS, RP0
MOVLW     b'xxxx0xxx'      ;Select TMR0, new
                           ;prescale value and
                           ;clock source
MOVWF     OPTION_REG
BCF      STATUS, RP0
    
```

TABLE 6-1: REGISTERS ASSOCIATED WITH TIMER0

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on POR	Value on All Other RESETS
01h	TMR0	Timer0 module register								xxxx xxxx	uuuu uuuu
0Bh/8Bh	INTCON	GIE	PEIE	TOIE	INTE	RBIE	TOIF	INTF	RBIF	0000 000x	0000 000u
81h	OPTION	RBPU	INTEDG	T0CS	T0SE	PSA	PS2	PS1	PS0	1111 1111	1111 1111
85h	TRISA	—	—	—	TRISA4	TRISA3	TRISA2	TRISA1	TRISA0	---1 1111	---1 1111

Legend: — = Unimplemented locations, read as '0', u = unchanged, x = unknown

Note: Shaded bits are not used by TMR0 module.

PIC16C62X

9.4 Power-on Reset (POR), Power-up Timer (PWRT), Oscillator Start-up Timer (OST) and Brown-out Reset (BOR)

9.4.1 POWER-ON RESET (POR)

The on-chip POR circuit holds the chip in RESET until VDD has reached a high enough level for proper operation. To take advantage of the POR, just tie the MCLR pin through a resistor to VDD. This will eliminate external RC components usually needed to create Power-on Reset. A maximum rise time for VDD is required. See Electrical Specifications for details.

The POR circuit does not produce an internal RESET when VDD declines.

When the device starts normal operation (exits the RESET condition), device operating parameters (voltage, frequency, temperature, etc.) must be met to ensure operation. If these conditions are not met, the device must be held in RESET until the operating conditions are met.

For additional information, refer to Application Note AN607, "Power-up Trouble Shooting".

9.4.2 POWER-UP TIMER (PWRT)

The Power-up Timer provides a fixed 72 ms (nominal) time-out on power-up only, from POR or Brown-out Reset. The Power-up Timer operates on an internal RC oscillator. The chip is kept in RESET as long as PWRT is active. The PWRT delay allows the VDD to rise to an acceptable level. A configuration bit, **PWRT**, can disable (if set) or enable (if cleared or programmed) the Power-up Timer. The Power-up Timer should always be enabled when Brown-out Reset is enabled.

The Power-up Time delay will vary from chip-to-chip and due to VDD, temperature and process variation. See DC parameters for details.

9.4.3 OSCILLATOR START-UP TIMER (OST)

The Oscillator Start-Up Timer (OST) provides a 1024 oscillator cycle (from OSC1 input) delay after the PWRT delay is over. This ensures that the crystal oscillator or resonator has started and stabilized.

The OST time-out is invoked only for XT, LP and HS modes and only on Power-on Reset or wake-up from SLEEP.

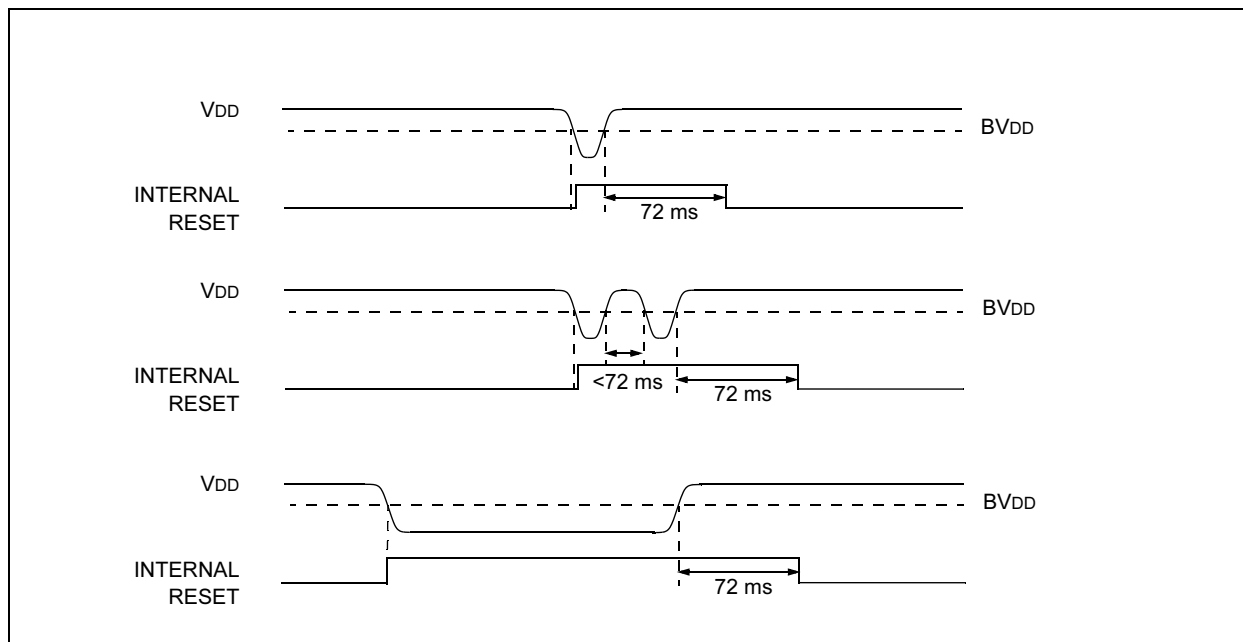
9.4.4 BROWN-OUT RESET (BOR)

The PIC16C62X members have on-chip Brown-out Reset circuitry. A configuration bit, **BODEN**, can disable (if clear/programmed) or enable (if set) the Brown-out Reset circuitry. If VDD falls below 4.0V refer to VBOR parameter D005 (VBOR) for greater than parameter (TBOR) in Table 12-5. The brown-out situation will RESET the chip. A RESET won't occur if VDD falls below 4.0V for less than parameter (TBOR).

On any RESET (Power-on, Brown-out, Watchdog, etc.) the chip will remain in RESET until VDD rises above BVDD. The Power-up Timer will now be invoked and will keep the chip in RESET an additional 72 ms.

If VDD drops below BVDD while the Power-up Timer is running, the chip will go back into a Brown-out Reset and the Power-up Timer will be re-initialized. Once VDD rises above BVDD, the Power-Up Timer will execute a 72 ms RESET. The Power-up Timer should always be enabled when Brown-out Reset is enabled. Figure 9-7 shows typical Brown-out situations.

FIGURE 9-7: BROWN-OUT SITUATIONS



PIC16C62X

FIGURE 9-11: EXTERNAL POWER-ON RESET CIRCUIT (FOR SLOW V_{DD} POWER-UP)

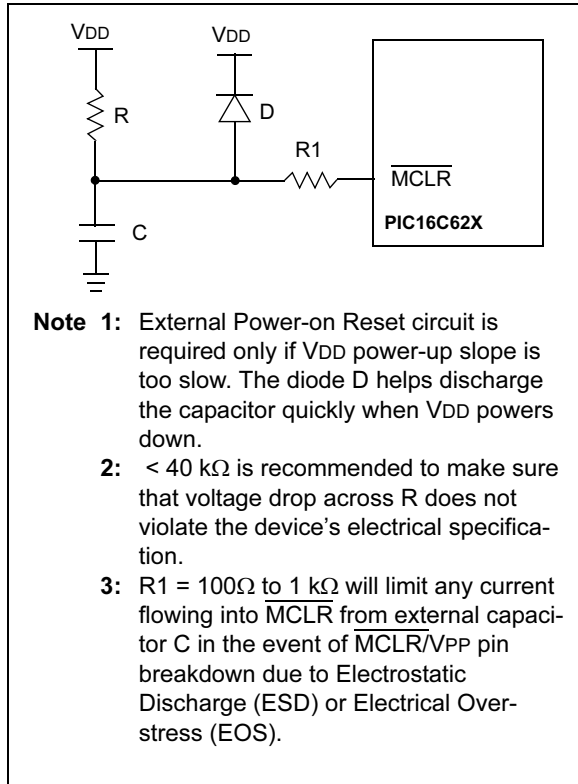


FIGURE 9-12: EXTERNAL BROWN-OUT PROTECTION CIRCUIT 1

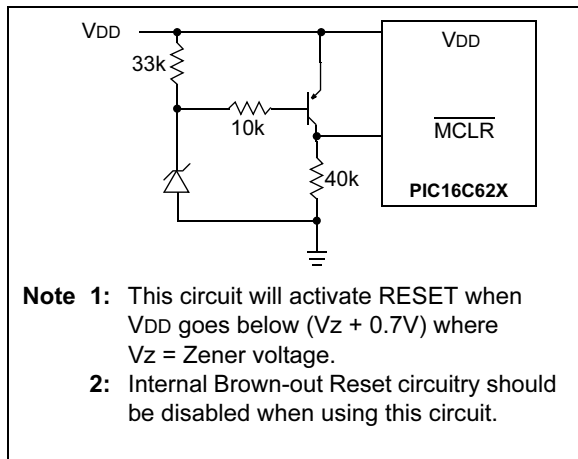


FIGURE 9-13: EXTERNAL BROWN-OUT PROTECTION CIRCUIT 2

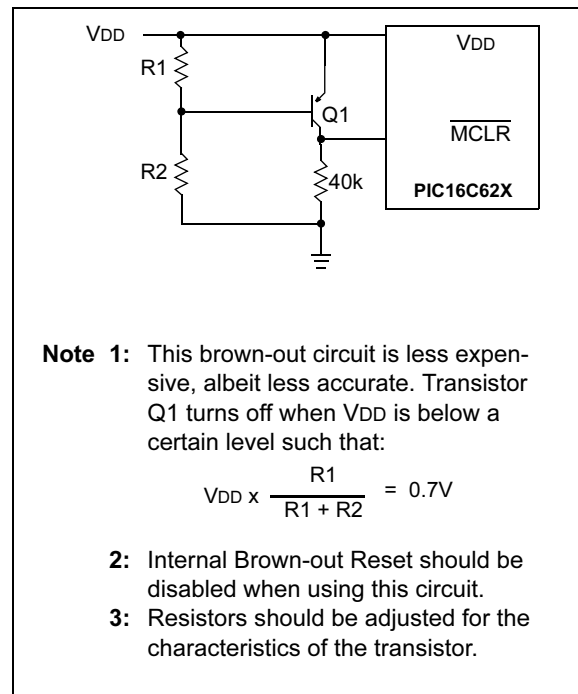
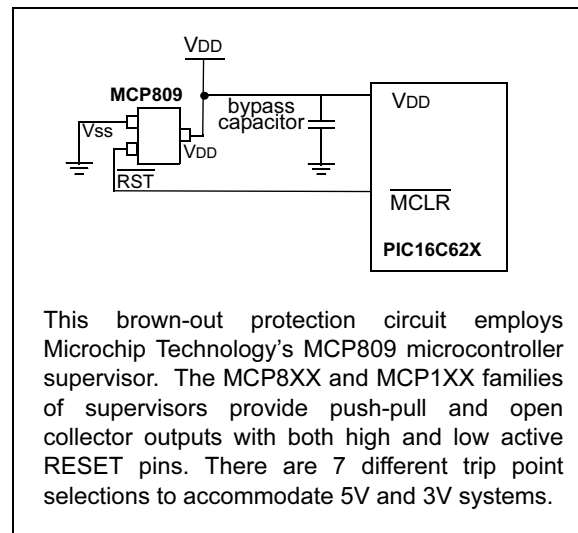


FIGURE 9-14: EXTERNAL BROWN-OUT PROTECTION CIRCUIT 3



PIC16C62X

9.5.1 RB0/INT INTERRUPT

External interrupt on RB0/INT pin is edge triggered, either rising if INTEDG bit (OPTION<6>) is set, or falling, if INTEDG bit is clear. When a valid edge appears on the RB0/INT pin, the INTF bit (INTCON<1>) is set. This interrupt can be disabled by clearing the INTE control bit (INTCON<4>). The INTF bit must be cleared in software in the interrupt service routine before re-enabling this interrupt. The RB0/INT interrupt can wake-up the processor from SLEEP, if the INTE bit was set prior to going into SLEEP. The status of the GIE bit decides whether or not the processor branches to the interrupt vector following wake-up. See Section 9.8 for details on SLEEP and Figure 9-18 for timing of wake-up from SLEEP through RB0/INT interrupt.

9.5.2 TMR0 INTERRUPT

An overflow (FFh → 00h) in the TMR0 register will set the T0IF (INTCON<2>) bit. The interrupt can be enabled/disabled by setting/clearing T0IE (INTCON<5>) bit. For operation of the Timer0 module, see Section 6.0.

9.5.3 PORTB INTERRUPT

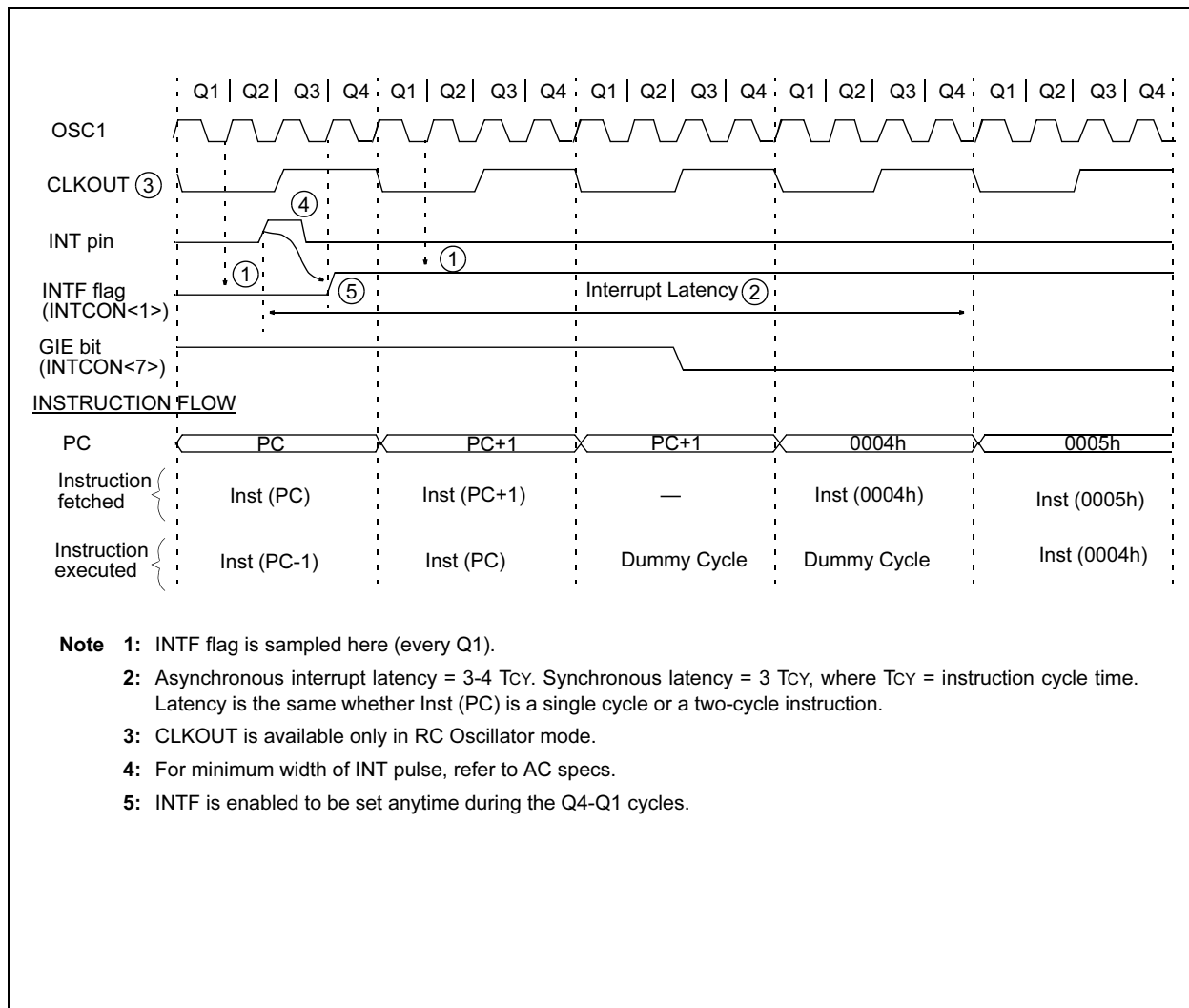
An input change on PORTB <7:4> sets the RBIF (INTCON<0>) bit. The interrupt can be enabled/disabled by setting/clearing the RBIE (INTCON<4>) bit. For operation of PORTB (Section 5.2).

Note: If a change on the I/O pin should occur when the read operation is being executed (start of the Q2 cycle), then the RBIF interrupt flag may not get set.

9.5.4 COMPARATOR INTERRUPT

See Section 7.6 for complete description of comparator interrupts.

FIGURE 9-16: INT PIN INTERRUPT TIMING



9.8 Power-Down Mode (SLEEP)

The Power-down mode is entered by executing a SLEEP instruction.

If enabled, the Watchdog Timer will be cleared but keeps running, the PD bit in the STATUS register is cleared, the TO bit is set, and the oscillator driver is turned off. The I/O ports maintain the status they had, before SLEEP was executed (driving high, low, or hi-impedance).

For lowest current consumption in this mode, all I/O pins should be either at VDD or VSS with no external circuitry drawing current from the I/O pin and the comparators and VREF should be disabled. I/O pins that are hi-impedance inputs should be pulled high or low externally to avoid switching currents caused by floating inputs. The T0CKI input should also be at VDD or VSS for lowest current consumption. The contribution from on chip pull-ups on PORTB should be considered.

The MCLR pin must be at a logic high level (VIHMC).

Note: It should be noted that a RESET generated by a WDT time-out does not drive MCLR pin low.

The first event will cause a device RESET. The two latter events are considered a continuation of program execution. The \overline{TO} and \overline{PD} bits in the STATUS register can be used to determine the cause of device RESET. PD bit, which is set on power-up, is cleared when SLEEP is invoked. \overline{TO} bit is cleared if WDT wake-up occurred.

When the SLEEP instruction is being executed, the next instruction (PC + 1) is pre-fetched. For the device to wake-up through an interrupt event, the corresponding interrupt enable bit must be set (enabled). Wake-up is regardless of the state of the GIE bit. If the GIE bit is clear (disabled), the device continues execution at the instruction after the SLEEP instruction. If the GIE bit is set (enabled), the device executes the instruction after the SLEEP instruction and then branches to the interrupt address (0004h). In cases where the execution of the instruction following SLEEP is not desirable, the user should have an NOP after the SLEEP instruction.

Note: If the global interrupts are disabled (GIE is cleared), but any interrupt source has both its interrupt enable bit and the corresponding interrupt flag bits set, the device will immediately wake-up from SLEEP. The SLEEP instruction is completely executed.

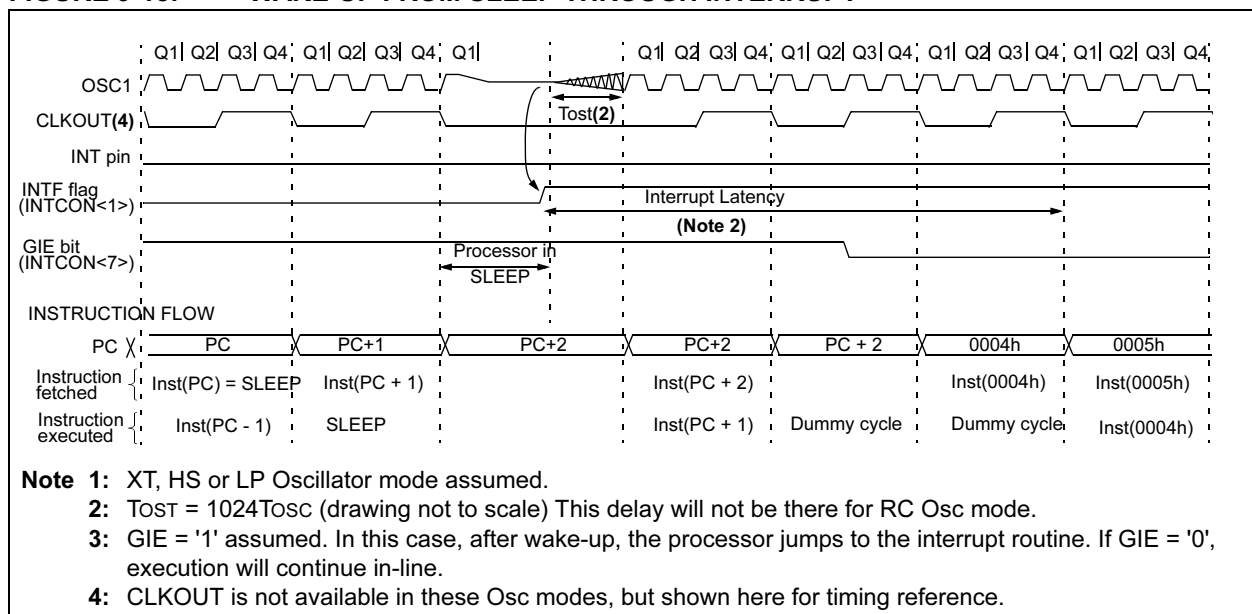
9.8.1 WAKE-UP FROM SLEEP

The device can wake-up from SLEEP through one of the following events:

1. External RESET input on MCLR pin
2. Watchdog Timer Wake-up (if WDT was enabled)
3. Interrupt from RB0/INT pin, RB Port change, or the Peripheral Interrupt (Comparator).

The WDT is cleared when the device wakes up from SLEEP, regardless of the source of wake-up.

FIGURE 9-18: WAKE-UP FROM SLEEP THROUGH INTERRUPT



10.1 Instruction Descriptions

ADDLW		Add Literal and W							
Syntax:	[<i>label</i>] ADDLW k								
Operands:	$0 \leq k \leq 255$								
Operation:	$(W) + k \rightarrow (W)$								
Status Affected:	C, DC, Z								
Encoding:	<table border="1"><tr><td>11</td><td>111x</td><td>kkkk</td><td>kkkk</td></tr></table>					11	111x	kkkk	kkkk
11	111x	kkkk	kkkk						
Description:	The contents of the W register are added to the eight bit literal 'k' and the result is placed in the W register.								
Words:	1								
Cycles:	1								
Example	ADDLW 0x15								
	Before Instruction								
	W = 0x10								
	After Instruction								
	W = 0x25								

ADDWF	Add W and f				
Syntax:	[<i>label</i>] ADDWF f,d				
Operands:	$0 \leq f \leq 127$ $d \in [0,1]$				
Operation:	$(W) + (f) \rightarrow (\text{dest})$				
Status Affected:	C, DC, Z				
Encoding:	<table><tr><td>00</td><td>0111</td><td>dfff</td><td>ffff</td></tr></table>	00	0111	dfff	ffff
00	0111	dfff	ffff		
Description:	Add the contents of the W register with register 'f'. If 'd' is 0, the result is stored in the W register. If 'd' is 1, the result is stored back in register 'f'.				
Words:	1				
Cycles:	1				
Example	ADDWF FSR, 0 Before Instruction W = 0x17 FSR = 0xC2 After Instruction W = 0xD9 FSR = 0xC2				

ANDLW		AND Literal with W						
Syntax:	[<i>label</i>] ANDLW k							
Operands:	$0 \leq k \leq 255$							
Operation:	$(W) .\text{AND}. (k) \rightarrow (W)$							
Status Affected:	Z							
Encoding:	<table border="1"><tr><td>11</td><td>1001</td><td>kkkk</td><td>kkkk</td></tr></table>				11	1001	kkkk	kkkk
11	1001	kkkk	kkkk					
Description:	The contents of W register are AND'ed with the eight bit literal 'k'. The result is placed in the W register.							
Words:	1							
Cycles:	1							
Example	ANDLW 0x5F							
	Before Instruction							
	W = 0xA3							
	After Instruction							
	W = 0x03							

ANDWF		AND W with f							
Syntax:	[<i>label</i>] ANDWF f,d								
Operands:	$0 \leq f \leq 127$ $d \in [0,1]$								
Operation:	(W) .AND. (f) \rightarrow (dest)								
Status Affected:	Z								
Encoding:	<table border="1"><tr><td>00</td><td>0101</td><td>dfff</td><td>ffff</td></tr></table>					00	0101	dfff	ffff
00	0101	dfff	ffff						
Description:	AND the W register with register 'f'. If 'd' is 0, the result is stored in the W register. If 'd' is 1, the result is stored back in register 'f'.								
Words:	1								
Cycles:	1								
Example	ANDWF FSR, 1								
	Before Instruction								
	W = 0x17								
	FSR = 0xC2								
	After Instruction								
	W = 0x17								
	FSR = 0x02								

SWAPF		Swap Nibbles in f							
Syntax:	[<i>label</i>] SWAPF f,d								
Operands:	$0 \leq f \leq 127$ $d \in [0,1]$								
Operation:	$(f<3:0>) \rightarrow (dest<7:4>),$ $(f<7:4>) \rightarrow (dest<3:0>)$								
Status Affected:	None								
Encoding:	<table><tr><td>00</td><td>1110</td><td>dfff</td><td>ffff</td></tr></table>					00	1110	dfff	ffff
00	1110	dfff	ffff						
Description:	The upper and lower nibbles of register 'f' are exchanged. If 'd' is 0, the result is placed in W register. If 'd' is 1, the result is placed in register 'f'.								
Words:	1								
Cycles:	1								
Example	SWAPF REG, 0								
	Before Instruction								
	REG1 = 0xA5								
	After Instruction								
	REG1 = 0xA5								
	W = 0x5A								

TRIS	Load TRIS Register				
Syntax:	[<i>label</i>] TRIS f				
Operands:	$5 \leq f \leq 7$				
Operation:	(W) → TRIS register f;				
Status Affected:	None				
Encoding:	<table><tr><td>00</td><td>0000</td><td>0110</td><td>0fff</td></tr></table>	00	0000	0110	0fff
00	0000	0110	0fff		
Description:	The instruction is supported for code compatibility with the PIC16C5X products. Since TRIS registers are readable and writable, the user can directly address them.				
Words:	1				
Cycles:	1				
Example	<table><tr><td>To maintain upward compatibility with future PICmicro[®] products, do not use this instruction.</td></tr></table>	To maintain upward compatibility with future PICmicro[®] products, do not use this instruction.			
To maintain upward compatibility with future PICmicro[®] products, do not use this instruction.					

XORLW		Exclusive OR Literal with W	
Syntax:	[<i>label</i> XORLW k 		

XORWF

Exclusive OR W with f

Syntax:

[*label*] XORWF f,d

Operands:

$0 \leq f \leq 127$
 $d \in [0,1]$

Operation:

(W) .XOR. (f) → (dest)

Status Affected:

Z

Encoding:

00	0110	dfff	ffff
----	------	------	------

Description:

Exclusive OR the contents of the W register with register 'f'. If 'd' is 0, the result is stored in the W register. If 'd' is 1, the result is stored back in register 'f'.

Words:

1

Cycles:

1

Example

XORWF REG 1

Before Instruction

REG = 0xAF

W = 0xB5

After Instruction

REG = 0x1A

W = 0xB5

PIC16C62X

NOTES:

12.0 ELECTRICAL SPECIFICATIONS

Absolute Maximum Ratings †

Ambient Temperature under bias	-40° to +125°C
Storage Temperature	-65° to +150°C
Voltage on any pin with respect to VSS (except VDD and $\overline{\text{MCLR}}$)	-0.6V to VDD +0.6V
Voltage on VDD with respect to VSS	0 to +7.5V
Voltage on $\overline{\text{MCLR}}$ with respect to VSS (Note 2)	0 to +14V
Voltage on RA4 with respect to VSS	8.5V
Total power Dissipation (Note 1)	1.0W
Maximum Current out of VSS pin	300 mA
Maximum Current into VDD pin	250 mA
Input Clamp Current, I _{IK} (V _I < 0 or V _I > VDD)	±20 mA
Output Clamp Current, I _{OK} (V _O < 0 or V _O > VDD)	±20 mA
Maximum Output Current sunk by any I/O pin	25 mA
Maximum Output Current sourced by any I/O pin	25 mA
Maximum Current sunk by PORTA and PORTB	200 mA
Maximum Current sourced by PORTA and PORTB	200 mA

Note 1: Power dissipation is calculated as follows: $P_{DIS} = V_{DD} \times \{I_{DD} - \sum I_{OH}\} + \sum \{(V_{DD} - V_{OH}) \times I_{OH}\} + \sum (V_{OL} \times I_{OL})$.

2: Voltage spikes below VSS at the $\overline{\text{MCLR}}$ pin, inducing currents greater than 80 mA, may cause latchup. Thus, a series resistor of 50-100Ω should be used when applying a "low" level to the $\overline{\text{MCLR}}$ pin rather than pulling this pin directly to VSS.

† **NOTICE:** Stresses above those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at those or any other conditions above those indicated in the operation listings of this specification is not implied. Exposure to maximum rating conditions for extended periods may affect device reliability.

12.1 DC Characteristics: PIC16C62X-04 (Commercial, Industrial, Extended) PIC16C62X-20 (Commercial, Industrial, Extended) PIC16LC62X-04 (Commercial, Industrial, Extended) (CONT.)

PIC16C62X		Standard Operating Conditions (unless otherwise stated) Operating temperature $-40^{\circ}\text{C} \leq T_A \leq +85^{\circ}\text{C}$ for industrial and $0^{\circ}\text{C} \leq T_A \leq +70^{\circ}\text{C}$ for commercial and $-40^{\circ}\text{C} \leq T_A \leq +125^{\circ}\text{C}$ for extended					
PIC16LC62X		Standard Operating Conditions (unless otherwise stated) Operating temperature $-40^{\circ}\text{C} \leq T_A \leq +85^{\circ}\text{C}$ for industrial and $0^{\circ}\text{C} \leq T_A \leq +70^{\circ}\text{C}$ for commercial and $-40^{\circ}\text{C} \leq T_A \leq +125^{\circ}\text{C}$ for extended Operating voltage V_{DD} range is the PIC16C62X range.					
Param No.	Sym	Characteristic	Min	Typ†	Max	Units	Conditions
D022	ΔI_{WDT}	WDT Current ⁽⁵⁾	—	6.0	20	μA	$V_{DD}=4.0\text{V}$ (125°C)
D022A	ΔI_{BOR}	Brown-out Reset Current ⁽⁵⁾	—	350	425	μA	BOD enabled, $V_{DD} = 5.0\text{V}$
D023	ΔI_{COMP}	Comparator Current for each Comparator ⁽⁵⁾	—	—	100	μA	$V_{DD} = 4.0\text{V}$
D023A	ΔI_{VREF}	VREF Current ⁽⁵⁾	—	—	300	μA	$V_{DD} = 4.0\text{V}$
D022	ΔI_{WDT}	WDT Current ⁽⁵⁾	—	6.0	15	μA	$V_{DD}=3.0\text{V}$
D022A	ΔI_{BOR}	Brown-out Reset Current ⁽⁵⁾	—	350	425	μA	BOD enabled, $V_{DD} = 5.0\text{V}$
D023	ΔI_{COMP}	Comparator Current for each Comparator ⁽⁵⁾	—	—	100	μA	$V_{DD} = 3.0\text{V}$
D023A	ΔI_{VREF}	VREF Current ⁽⁵⁾	—	—	300	μA	$V_{DD} = 3.0\text{V}$
1A	FOSC	LP Oscillator Operating Frequency	0	—	200	kHz	All temperatures
		RC Oscillator Operating Frequency	0	—	4	MHz	All temperatures
		XT Oscillator Operating Frequency	0	—	4	MHz	All temperatures
		HS Oscillator Operating Frequency	0	—	20	MHz	All temperatures
1A	FOSC	LP Oscillator Operating Frequency	0	—	200	kHz	All temperatures
		RC Oscillator Operating Frequency	0	—	4	MHz	All temperatures
		XT Oscillator Operating Frequency	0	—	4	MHz	All temperatures
		HS Oscillator Operating Frequency	0	—	20	MHz	All temperatures

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: This is the limit to which V_{DD} can be lowered without losing RAM data.

2: The supply current is mainly a function of the operating voltage and frequency. Other factors such as I/O pin loading and switching rate, oscillator type, internal code execution pattern, and temperature also have an impact on the current consumption.

The test conditions for all I_{DD} measurements in Active Operation mode are:

OSC1 = external square wave, from rail to rail; all I/O pins tri-stated, pulled to V_{DD} ,

MCLR = V_{DD} ; WDT enabled/disabled as specified.

3: The power-down current in SLEEP mode does not depend on the oscillator type. Power-down current is measured with the part in SLEEP mode, with all I/O pins in hi-impedance state and tied to V_{DD} or V_{SS} .

4: For RC osc configuration, current through REXT is not included. The current through the resistor can be estimated by the formula: $I_r = V_{DD}/2R_{EXT}$ (mA) with R_{EXT} in k Ω .

5: The Δ current is the additional current consumed when this peripheral is enabled. This current should be added to the base I_{DD} or I_{PD} measurement.

PIC16C62X

12.2 DC Characteristics: PIC16C62XA-04 (Commercial, Industrial, Extended) PIC16C62XA-20 (Commercial, Industrial, Extended) PIC16LC62XA-04 (Commercial, Industrial, Extended)

PIC16C62XA		Standard Operating Conditions (unless otherwise stated) Operating temperature $-40^{\circ}\text{C} \leq T_A \leq +85^{\circ}\text{C}$ for industrial and $0^{\circ}\text{C} \leq T_A \leq +70^{\circ}\text{C}$ for commercial and $-40^{\circ}\text{C} \leq T_A \leq +125^{\circ}\text{C}$ for extended					
PIC16LC62XA		Standard Operating Conditions (unless otherwise stated) Operating temperature $-40^{\circ}\text{C} \leq T_A \leq +85^{\circ}\text{C}$ for industrial and $0^{\circ}\text{C} \leq T_A \leq +70^{\circ}\text{C}$ for commercial and $-40^{\circ}\text{C} \leq T_A \leq +125^{\circ}\text{C}$ for extended					
Param. No.	Sym	Characteristic	Min	Typ†	Max	Units	Conditions
D001	VDD	Supply Voltage	3.0	—	5.5	V	See Figures 12-1, 12-2, 12-3, 12-4, and 12-5
D001	VDD	Supply Voltage	2.5	—	5.5	V	See Figures 12-1, 12-2, 12-3, 12-4, and 12-5
D002	VDR	RAM Data Retention Voltage ⁽¹⁾	—	1.5*	—	V	Device in SLEEP mode
D002	VDR	RAM Data Retention Voltage ⁽¹⁾	—	1.5*	—	V	Device in SLEEP mode
D003	VPOR	VDD start voltage to ensure Power-on Reset	—	VSS	—	V	See section on Power-on Reset for details
D003	VPOR	VDD start voltage to ensure Power-on Reset	—	VSS	—	V	See section on Power-on Reset for details
D004	SVDD	VDD rise rate to ensure Power-on Reset	0.05*	—	—	V/ms	See section on Power-on Reset for details
D004	SVDD	VDD rise rate to ensure Power-on Reset	0.05*	—	—	V/ms	See section on Power-on Reset for details
D005	VBOR	Brown-out Detect Voltage	3.7	4.0	4.35	V	BOREN configuration bit is cleared
D005	VBOR	Brown-out Detect Voltage	3.7	4.0	4.35	V	BOREN configuration bit is cleared

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: This is the limit to which VDD can be lowered without losing RAM data.

2: The supply current is mainly a function of the operating voltage and frequency. Other factors such as I/O pin loading and switching rate, oscillator type, internal code execution pattern, and temperature also have an impact on the current consumption.

The test conditions for all IDD measurements in Active Operation mode are:

OSC1 = external square wave, from rail to rail; all I/O pins tri-stated, pulled to VDD,

MCLR = VDD; WDT enabled/disabled as specified.

3: The power-down current in SLEEP mode does not depend on the oscillator type. Power-down current is measured with the part in SLEEP mode, with all I/O pins in hi-impedance state and tied to VDD or VSS.

4: For RC osc configuration, current through REXT is not included. The current through the resistor can be estimated by the formula: $I_r = V_{DD}/2R_{EXT}$ (mA) with REXT in kΩ.

5: The Δ current is the additional current consumed when this peripheral is enabled. This current should be added to the base IDD or IPD measurement.

6: Commercial temperature range only.

12.3 DC CHARACTERISTICS: PIC16CR62XA-04 (Commercial, Industrial, Extended) PIC16CR62XA-20 (Commercial, Industrial, Extended) PIC16LCR62XA-04 (Commercial, Industrial, Extended)

PIC16CR62XA-04 PIC16CR62XA-20			Standard Operating Conditions (unless otherwise stated) Operating temperature $-40^{\circ}\text{C} \leq T_A \leq +85^{\circ}\text{C}$ for industrial and $0^{\circ}\text{C} \leq T_A \leq +70^{\circ}\text{C}$ for commercial and $-40^{\circ}\text{C} \leq T_A \leq +125^{\circ}\text{C}$ for extended				
PIC16LCR62XA-04			Standard Operating Conditions (unless otherwise stated) Operating temperature $-40^{\circ}\text{C} \leq T_A \leq +85^{\circ}\text{C}$ for industrial and $0^{\circ}\text{C} \leq T_A \leq +70^{\circ}\text{C}$ for commercial and $-40^{\circ}\text{C} \leq T_A \leq +125^{\circ}\text{C}$ for extended				
Param. No.	Sym	Characteristic	Min	Typ†	Max	Units	Conditions
D001	VDD	Supply Voltage	3.0	—	5.5	V	See Figures 12-7, 12-8, 12-9
D001	VDD	Supply Voltage	2.5	—	5.5	V	See Figures 12-7, 12-8, 12-9
D002	VDR	RAM Data Retention Voltage ⁽¹⁾	—	1.5*	—	V	Device in SLEEP mode
D002	VDR	RAM Data Retention Voltage ⁽¹⁾	—	1.5*	—	V	Device in SLEEP mode
D003	VPOR	VDD start voltage to ensure Power-on Reset	—	VSS	—	V	See section on Power-on Reset for details
D003	VPOR	VDD start voltage to ensure Power-on Reset	—	VSS	—	V	See section on Power-on Reset for details
D004	SVDD	VDD rise rate to ensure Power-on Reset	0.05*	—	—	V/ms	See section on Power-on Reset for details
D004	SVDD	VDD rise rate to ensure Power-on Reset	0.05*	—	—	V/ms	See section on Power-on Reset for details
D005	VBOR	Brown-out Detect Voltage	3.7	4.0	4.35	V	BOREN configuration bit is cleared
D005	VBOR	Brown-out Detect Voltage	3.7	4.0	4.35	V	BOREN configuration bit is cleared
D010	IDD	Supply Current ⁽²⁾	—	1.2	1.7	mA	FOSC = 4 MHz, VDD = 5.5V, WDT disabled, XT mode, (Note 4)*
			—	500	900	μA	FOSC = 4 MHz, VDD = 3.0V, WDT disabled, XT mode, (Note 4)
			—	1.0	2.0	mA	FOSC = 10 MHz, VDD = 3.0V, WDT disabled, HS mode, (Note 6)
			—	4.0	7.0	mA	FOSC = 20 MHz, VDD = 5.5V, WDT disabled*, HS mode
			—	3.0	6.0	mA	FOSC = 20 MHz, VDD = 4.5V, WDT disabled, HS mode
			—	35	70	μA	FOSC = 32 kHz, VDD = 3.0V, WDT disabled, LP mode
D010	IDD	Supply Current ⁽²⁾	—	1.2	1.7	mA	FOSC = 4.0 MHz, VDD = 5.5V, WDT disabled, XT mode, (Note 4)*
			—	400	800	μA	FOSC = 4.0 MHz, VDD = 2.5V, WDT disabled, XT mode (Note 4)
			—	35	70	μA	FOSC = 32 kHz, VDD = 2.5V, WDT disabled, LP mode

12.4 DC Characteristics: PIC16C62X/C62XA/CR62XA (Commercial, Industrial, Extended) PIC16LC62X/LC62XA/LCR62XA (Commercial, Industrial, Extended) (CONT.)

PIC16C62X/C62XA/CR62XA			Standard Operating Conditions (unless otherwise stated) Operating temperature $-40^{\circ}\text{C} \leq T_A \leq +85^{\circ}\text{C}$ for industrial and $0^{\circ}\text{C} \leq T_A \leq +70^{\circ}\text{C}$ for commercial and $-40^{\circ}\text{C} \leq T_A \leq +125^{\circ}\text{C}$ for extended				
PIC16LC62X/LC62XA/LCR62XA			Standard Operating Conditions (unless otherwise stated) Operating temperature $-40^{\circ}\text{C} \leq T_A \leq +85^{\circ}\text{C}$ for industrial and $0^{\circ}\text{C} \leq T_A \leq +70^{\circ}\text{C}$ for commercial and $-40^{\circ}\text{C} \leq T_A \leq +125^{\circ}\text{C}$ for extended				
Param. No.	Sym	Characteristic	Min	Typ†	Max	Units	Conditions
D040	V _{IH}	Input High Voltage I/O ports with TTL buffer	2.0V 0.25 V _{DD} + 0.8V	—	V _{DD} V _{DD}	V	V _{DD} = 4.5V to 5.5V otherwise
D041		with Schmitt Trigger input	0.8 V _{DD}	—	V _{DD}		
D042		$\overline{\text{MCLR}}$ RA4/T0CKI	0.8 V _{DD}	—	V _{DD}	V	
D043 D043A		OSC1 (XT, HS and LP) OSC1 (in RC mode)	0.7 V _{DD} 0.9 V _{DD}	—	V _{DD}	V	(Note 1)
D070	I _{PURB}	PORTB weak pull-up current	50	200	400	μA	V _{DD} = 5.0V, V _{PIN} = V _{SS}
D070	I _{PURB}	PORTB weak pull-up current	50	200	400	μA	V _{DD} = 5.0V, V _{PIN} = V _{SS}
D060	I _{IL}	Input Leakage Current ^(2, 3) I/O ports (Except PORTA)			±1.0	μA	V _{SS} ≤ V _{PIN} ≤ V _{DD} , pin at hi-impedance
D061		PORTA	—	—	±0.5	μA	V _{SS} ≤ V _{PIN} ≤ V _{DD} , pin at hi-impedance
D063		RA4/T0CKI	—	—	±1.0	μA	V _{SS} ≤ V _{PIN} ≤ V _{DD}
D063		OSC1, $\overline{\text{MCLR}}$	—	—	±5.0	μA	V _{SS} ≤ V _{PIN} ≤ V _{DD} , XT, HS and LP osc configuration
D060	I _{IL}	Input Leakage Current ^(2, 3) I/O ports (Except PORTA)			±1.0	μA	V _{SS} ≤ V _{PIN} ≤ V _{DD} , pin at hi-impedance
D061		PORTA	—	—	±0.5	μA	V _{SS} ≤ V _{PIN} ≤ V _{DD} , pin at hi-impedance
D063		RA4/T0CKI	—	—	±1.0	μA	V _{SS} ≤ V _{PIN} ≤ V _{DD}
D063		OSC1, $\overline{\text{MCLR}}$	—	—	±5.0	μA	V _{SS} ≤ V _{PIN} ≤ V _{DD} , XT, HS and LP osc configuration
D080	V _{OL}	Output Low Voltage I/O ports	—	—	0.6	V	I _{OL} = 8.5 mA, V _{DD} = 4.5V, -40° to $+85^{\circ}\text{C}$
			—	—	0.6	V	I _{OL} = 7.0 mA, V _{DD} = 4.5V, $+125^{\circ}\text{C}$
D083		OSC2/CLKOUT (RC only)	—	—	0.6	V	I _{OL} = 1.6 mA, V _{DD} = 4.5V, -40° to $+85^{\circ}\text{C}$
			—	—	0.6	V	I _{OL} = 1.2 mA, V _{DD} = 4.5V, $+125^{\circ}\text{C}$

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: In RC oscillator configuration, the OSC1 pin is a Schmitt Trigger input. It is not recommended that the PIC16C62X(A) be driven with external clock in RC mode.

2: The leakage current on the $\overline{\text{MCLR}}$ pin is strongly dependent on applied voltage level. The specified levels represent normal operating conditions. Higher leakage current may be measured at different input voltages.

3: Negative current is defined as coming out of the pin.

12.8 Timing Parameter Symbolology

The timing parameter symbols have been created with one of the following formats:

- 1. TppS2ppS
- 2. TppS

T			
F	Frequency	T	Time
Lowercase subscripts (pp) and their meanings:			
pp			
ck	CLKOUT	osc	OSC1
io	I/O port	t0	T0CKI
mc	MCLR		
Uppercase letters and their meanings:			
S			
F	Fall	P	Period
H	High	R	Rise
I	Invalid (Hi-impedance)	V	Valid
L	Low	Z	Hi-Impedance

FIGURE 12-11: LOAD CONDITIONS

